

# Application Note 8 External Set Up and Hold Time Bipolar Arrays

CHAP 12 - APPLICATION NOTE 8  
EXTERNAL SET UP AND HOLD TIME, BIPOLAR ARRAYS

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## EXTERNAL SET-UP and HOLD TIMES - 100% ECL

The basic external set-up and hold time equations for an ECL-only circuit are outlined below. Asynchronous  $T_{PLH}$  and  $T_{PHL}$  skews must also be taken into account by computing set-up and hold time for both rising and falling edges.

$$T_{su(\text{external})} = [SU + (M-1) * |SU|] + T_{su(\text{macro})} + (T_{DM} - T_{CM})$$

$$T_{h(\text{external})} = [HL + (M-1) * |HL|] + T_{h(\text{macro})} + (T_{DM} - T_{CM})$$

Where:

$T_D$  = data path propagation delay from the circuit input and up to the memory macro data input pin

$T_C$  = clock path propagation delay from the circuit input and up to the memory macro clock input pin

$$SU = (1.1 T_D - 0.9 T_C)$$

$$HL = (1.1 T_C - 0.9 T_D)$$

M = commercial grade or military grade multiplier  
(refer to the multiplication factor table)

$T_{DM}$  = interconnect wire length in excess of 100mils/net in the data path

$T_{CM}$  = interconnect wire length in excess of 100mils/net in the clock path

$T_{su(\text{macro})}$  =  $T_{su}$  as specified in Design Guide (SPEC = MIN)

$T_{h(\text{macro})}$  =  $T_h$  as specified in Design Guide (SPEC = MIN)

FIGURE 1

EXTERNAL SET-UP AND HOLD FOR ECL ONLY CIRCUIT

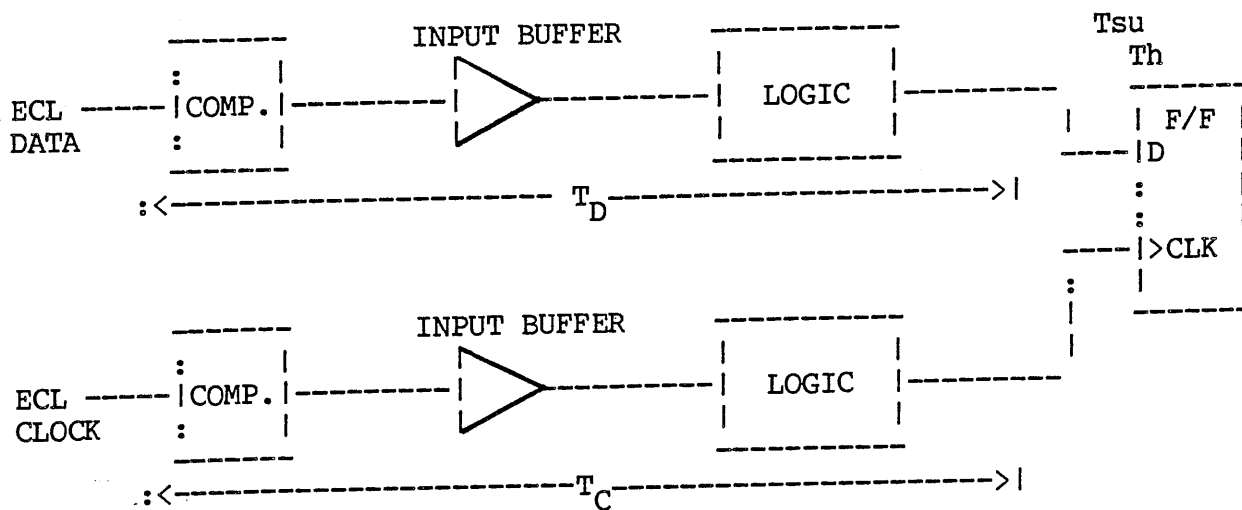
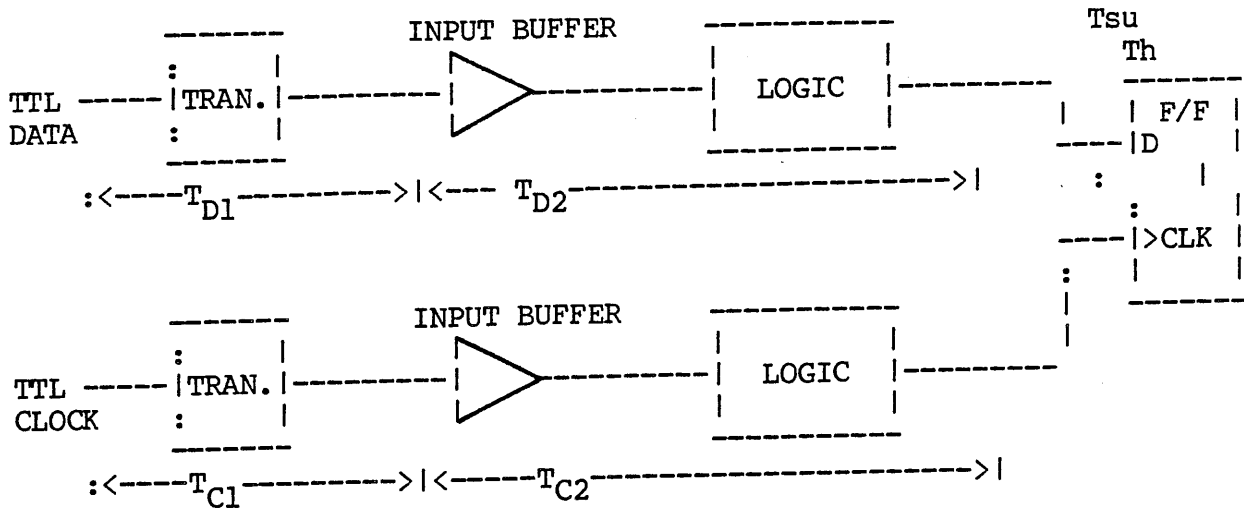


FIGURE 2

EXTERNAL SET-UP AND HOLD FOR TTL ONLY CIRCUIT



## EXTERNAL SET-UP and HOLD TIMES - 100% TTL

The basic external set-up and hold time equations for a TTL-only circuit are outlined below. Asynchronous  $T_{PLH}$  and  $T_{PHL}$  skews must also be taken into account by computing set-up and hold time for both rising and falling edges.

$$T_{su(\text{external})} = [SU1 + (M1-1) * |SU1|] + [SU2 + (M2-1) * |SU2|] \\ + T_{su(\text{macro})} + (T_{DM} - T_{CM})$$

$$T_{h(\text{external})} = [HL1 + (M1-1) * |HL1|] + [HL2 + (M2-1) * |HL2|] \\ + T_{h(\text{macro})} + (T_{DM} - T_{CM})$$

Where:

$T_{D2}$  = data path propagation delay from the circuit input and up to the memory macro data input pin; exclude the TTL input translator delay

$T_{C2}$  = clock path propagation delay from the circuit input and up to the memory macro clock input pin; exclude the TTL input translator delay

$T_{D1}$  = data path propagation delay from the TTL input translator

$T_{C1}$  = clock path propagation delay from the TTL input translator

$$SU1 = (1.1 T_{D1} - 0.9 T_{C1})$$

$$HL1 = (1.1 T_{C1} - 0.9 T_{D1})$$

$$SU2 = (1.1 T_{D2} - 0.9 T_{C2})$$

$$HL2 = (1.1 T_{C2} - 0.9 T_{D2})$$

M1 = commercial grade or military grade multiplier - TTL inputs only

M2 = multiplier for internal delays  
(refer to the multiplication factor table)

$T_{DM}$  = interconnect wire length in excess of 100mils/net  
in the data path

$T_{CM}$  = interconnect wire length in excess of 100mils/net  
in the clock path

$T_{su(\text{macro})}$  =  $T_{su}$  as specified in Design Guide  
(specified as minimum)

$T_{h(\text{macro})}$  =  $T_h$  as specified in Design Guide  
(specified as minimum)

## EXTERNAL SET-UP and HOLD TIMES - ECL DATA AND TTL CLOCK

The basic external set-up and hold time equations for an ECL-DATA and TTL-CLOCK circuit are outlined below. Asynchronous  $T_{PLH}$  and  $T_{PHL}$  skews must also be taken into account by computing set-up and hold time for both rising and falling edges.

$$T_{su(external)} = [SU + (M2-1) * |SU|] + T_{su(macro)} + (T_{DM} - T_{CM})$$

$$T_{h(external)} = [M1 * T_{C_{translator}}] + [HL + (M2-1) * |HL|] + T_{h(macro)} + (T_{DM} - T_{CM})$$

Where:

$T_D$  = data path propagation delay from the circuit input and up to the memory macro data input pin

$T_C$  = clock path propagation delay from the circuit input and up to the memory macro clock input pin; excluding input translator delay

$T_{C_{translator}}$  = clock path delay due to input translator

$$SU = (1.1 T_D - 0.9 T_C)$$

$$HL = (1.1 T_C - 0.9 T_D)$$

M1 = commercial grade or military grade multiplier - TTL inputs only

M2 = multiplier for internal delays  
(refer to the multiplication factor table)

$T_{DM}$  = interconnect wire length in excess of 100mils/net in the data path

$T_{CM}$  = interconnect wire length in excess of 100mils/net in the clock path

$T_{su(macro)}$  =  $T_{su}$  as specified in Design Guide (SPEC = MIN)

$T_{h(macro)}$  =  $T_h$  as specified in Design Guide (SPEC = MIN)



## EXTERNAL SET-UP and HOLD TIMES - TTL DATA AND ECL CLOCK

The basic external set-up and hold time equations for a TTL-DATA and ECL-CLOCK circuit are outlined below. Asynchronous  $T_{PLH}$  and  $T_{PHL}$  skews must also be taken into account by computing set-up and hold time for both rising and falling edges.

$$T_{su(\text{external})} = [M1 * T_{D_{\text{translator}}} ] + [SU + (M2-1) * |SU|] \\ + T_{su(\text{macro})} + (T_{DM} - T_{CM})$$

$$T_{h(\text{external})} = [(M1-1) * T_{D_{\text{translator}}} ] + [HL + (M2-1) * |HL|] \\ + T_{h(\text{macro})} + (T_{DM} - T_{CM})$$

Where:

$T_D$  = data path propagation delay from the circuit input and up to the memory macro data input pin; excluding the TTL input translator delay

$T_{D_{\text{translator}}}$  = data path delay due to TTL input translator

$T_C$  = clock path propagation delay from the circuit input and up to the memory macro clock input pin

$$SU = (1.1 T_D - 0.9 T_C)$$

$$HL = (1.1 T_C - 0.9 T_D)$$

M1 = commercial grade or military grade multiplier - TTL inputs only

M2 = multiplier for internal delays  
(refer to the multiplication factor table)

$T_{DM}$  = interconnect wire length in excess of 100mils/net in the data path

$T_{CM}$  = interconnect wire length in excess of 100mils/net in the clock path

$T_{su(\text{macro})}$  =  $T_{su}$  as specified in Design Guide (SPEC = MIN)

$T_{h(\text{macro})}$  =  $T_h$  as specified in Design Guide (SPEC = MIN)

TABLE 10  
 TYPICAL LOADING DELAY DELTA Tpd

MACRO TYPE	RISE/FALL DELTA Tpd
S OPTION	0.05/0.10 ns/load
H OPTION	0.05/0.10 ns/load
P OPTION	0.05/0.10 ns/load
DRIVERS	0.05/0.10 ns/load

 TABLE 11  
 TYPICAL WIRE-OR DELAY DELTA Tpd

NET SIZE	RISE/FALL DELTA Tpd
WIREOR2	0.05/0.1 ns
WIREOR3	0.10/0.2 ns
WIREOR4	0.15/0.3 ns

 TABLE 12  
 WORST-CASE DELAY MULTIPLICATION FACTORS

1.5	--- For COMMERCIAL applications (ALL BUT TTL INPUT MACROS) 0°C to 70°C, ±5% power supplies
2.0	--- FOR TTL INPUTS - COMMERCIAL APPLICATIONS
1.6	--- For MILITARY applications (ALL BUT TTL INPUT MACROS) -55°C ambient to +125°C case ±10% power supplies
2.5	--- FOR TTL INPUTS - MILITARY APPLICATIONS

 TABLE 13  
 TYPICAL METAL DELAYS

First metal	7ps/mil
Second metal	4ps/mil

# Q3500

TABLE 9  
TYPICAL LOADING DELAY DELTA Tpd

MACRO TYPE	RISE/FALL DELTA Tpd
S OPTION	0.03/0.05 ns/load
H OPTION	0.03/0.05 ns/load
L OPTION	0.03/0.10 ns/load
15-Load DRIVERS	0.03/0.03 ns/load

TABLE 10  
TYPICAL WIRE-OR DELAY DELTA Tpd

NET SIZE	RISE/FALL DELTA Tpd
WIREOR2	0.10/0.05 ns
WIREOR3	0.20/0.05 ns
WIREOR4	0.30/0.05 ns

TABLE 11  
WORST-CASE DELAY MULTIPLICATION FACTORS

- 1.5 --- For COMMERCIAL applications \*  
0°C to 70°C, ±5% power supplies
- 1.6 --- For MILITARY applications \*\*  
-55°C ambient to +125°C case  
±10% power supplies

\*  $T_j \leq 130^\circ\text{C}$

\*\*  $T_j \leq 150^\circ\text{C}$